

**What is claimed is:**

1           1. A dual chips stacked packaging structure,  
2 comprising:

3           a first chip, having an active surface and an  
4           opposing non-active surface, the active surface  
5           consisting of a central area and a peripheral  
6           area having a plurality of first bonding pads;

7           a lead frame, comprising a plurality of leads and a  
8           chip paddle having a first adhering surface and  
9           a second adhering surface, the first adhering  
10          surface adhered to the active surface of the  
11          first chip in such a way as to avoid contact  
12          with the first bonding pads;

13          a second chip, having an active surface and an  
14          opposing non-active surface connecting with the  
15          second adhering surface of the chip paddle, the  
16          active surface consisting of a central area and  
17          a peripheral area having a plurality of second  
18          bonding pads; and

19          a plurality of wires, wherein parts of the wires  
20          electrically connect with the first bonding pad  
21          and the leads, and parts of the wires  
22          electrically connect with the second bonding  
23          pad and the leads.

1           2. The structure as claimed in claim 1, wherein  
2 the first adhering surface of the chip paddle and the  
3 active surface of the first chip are adhered by a non-  
4 conductive solid or liquid adhesive.

1           3.    The structure as claimed in claim 1, wherein  
2    the second adhering surface of the chip paddle and the  
3    non-active surface of the second chip are connected by a  
4    solid                    or                    liquid                    adhesive.

1           4.    The structure as claimed in claim 1, wherein  
2    the wires are metal lines.

1           5.    A dual chips stacked packaging structure,  
2    comprising:

3           a first chip, having an active surface and an  
4                opposing non-active surface, wherein the active  
5                surface consists of a central area and a  
6                peripheral area having a plurality of first  
7                bonding pads;

8           a lead frame comprising a plurality of leads and a  
9                chip paddle having a first adhering surface and  
10              a second adhering surface, the first adhering  
11              surface adhered to the active surface of the  
12              first chip in such a way as to avoid contact  
13              with the first bonding pads;

14          a second chip, having an active surface and an  
15              opposing non-active surface connecting with the  
16              second adhering surface of the chip paddle,  
17              wherein the active surface consists of a  
18              central area and a peripheral area having a  
19              plurality of second bonding pads;

20          a plurality of wires, parts of which electrically  
21              connect with the first bonding pad and the

22                   leads, and parts of which electrically connect  
23                   with the second bonding pad and the leads; and  
24           an encapsulation, covering the lead frame, the first  
25           chip, the second chip, and the wires.

1           6.    The structure as claimed in claim 5, wherein  
2   each lead further comprises an inner lead covered by the  
3   encapsulation and outer lead extending beyond the  
4   encapsulation.

1           7.    The structure as claimed in claim 5, wherein  
2   the first adhering surface of the chip paddle and the  
3   active surface of the first chip are adhered by a non-  
4   conductive solid or liquid adhesive.

1           8.    The structure as claimed in claim 5, wherein  
2   the second adhering surface of the chip paddle and the  
3   non-active surface of the second chip are connected by a  
4   solid or liquid adhesive.

1           9.    The structure as claimed in claim 5, wherein  
2   the wires are metal lines.

1           10.   A dual chips stacked packaging structure,  
2   comprising:

3           a first chip, having an active surface and an  
4           opposing non-active surface, wherein the active  
5           surface consists of a central area and a  
6           peripheral area having a plurality of first  
7           bonding pads;

8           a lead frame, comprising a plurality of leads and a  
9           chip paddle having a first adhering surface and

10 a second adhering surface, the first adhering  
11 surface adhered to the active surface of the  
12 first chip in such a way as to avoid contact  
13 with the first bonding pads, and each of the  
14 leads comprising a wire connecting surface and  
15 a wire non-connecting surface;

16 a second chip, having an active surface and an  
17 opposing non-active surface connecting with the  
18 second adhering surface of the chip paddle,  
19 wherein the active surface consists of a  
20 central area and a peripheral area having a  
21 plurality of second bonding pads;

22 a plurality of wires, parts of which electrically  
23 connect with the first bonding pad and the  
24 leads, and parts which of electrically connect  
25 with the second bonding pad and the leads; and

26 an encapsulation, covering the chip paddle, the  
27 second chip, the wire connecting surface of the  
28 leads, the active surface of the first chip,  
29 and the wires, with the non-active surface of  
30 the first chip and the wire non-connecting  
31 surface of the leads exposed beyond the  
32 encapsulation.

1 11. The structure as claimed in claim 10, wherein  
2 each lead further comprises an inner lead covered by the  
3 encapsulation and outer lead extending beyond the  
4 encapsulation.

1 12. The structure as claimed in claim 10, wherein  
2 the first adhering surface of the chip paddle and the

3 active surface of the first chip are adhered by a non-  
4 conductive solid or liquid adhesive.

1 13. The structure as claimed in claim 10, wherein  
2 the second adhering surface of the chip paddle and the  
3 non-active surface of the second chip are connected by a  
4 solid or liquid adhesive.

1 14. The structure as claimed in claim 10, wherein  
2 the wires are metal lines.